

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MITSUYA UTSUNO	09/24/2020
YAN ZHANG	09/24/2020
YOSHIO SUSA	09/28/2020
ATSUKI FUKAZAWA	10/01/2020
RECEIVING PARTY DATA	
Name:	ASM IP HOLDING B.V.
Street Address:	VERSTERKERSTRAAT 8
City:	ALMERE
State/Country:	NETHERLANDS
Postal Code:	1322 AP
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16950899
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	PAT-JPN-0490-US-NP
NAME OF SUBMITTER:	MICHELLE SYMPSON
SIGNATURE:	/Michelle Simpson/
DATE SIGNED:	11/20/2020
Total Attachments: 3	
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Filing Date: November 17, 2020

Title: SUBSTRATE PROCESSING DEVICE HAVING CONNECTION PLATES,
SUBSTRATE PROCESSING METHOD

ASSIGNMENT

WHEREAS, Mitsuya UTSUNO, a citizen of Japan and a resident of Tachikawa-shi, Tokyo, Japan; Yan ZHANG, a citizen of China and a resident of Tama-shi, Tokyo, Japan; Yoshio SUSA, a citizen of Japan and a resident of Tama-shi, Tokyo, Japan; Atsuki FUKAZAWA, a citizen of Japan and a resident of Tama-shi, Tokyo, Japan,

(collectively, “WE” or “ASSIGNOR”) have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to SUBSTRATE PROCESSING DEVICE HAVING CONNECTION PLATES, SUBSTRATE PROCESSING METHOD (collectively, the “INVENTIONS”) for which WE have executed and/or may execute one or more patent applications therefore; and

WHEREAS, ASM IP HOLDING B.V. (hereinafter “ASSIGNEE”), a corporation having a place of business at Versterkerstraat 8, Almere, 1322 AP, Netherlands, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all patent applications therefore, and all patents that have granted or may be granted hereafter thereon, including, but not limited to, those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed and transferred, and by these presents do hereby sell, assign, convey and transfer, unto ASSIGNEE, its successors, its legal representatives and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefore that may have been filed or may be filed hereafter for said INVENTIONS (including but not limited Application No(s). 16/950,899, filed on November 17, 2020, as Docket No. PAT-JPN-0490-US-NP (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known)) and all rights of priority under International Conventions, Treaties, and Agreements, all utility applications, national phase applications, utility model applications, divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications and design applications thereof, and all issued patents which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon;

AND WE DO HEREBY authorize and request any Official of any country or countries whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to

Application Serial No.: _____

Docket No.: PAT-JPN-0490-US-NP

Filing Date: _____

Title: SUBSTRATE PROCESSING DEVICE HAVING CONNECTION PLATES,
SUBSTRATE PROCESSING METHOD

ASSIGNEE, its successors, its legal representatives, and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover and retain damages and any ongoing or prospective royalties to which WE may be entitled, or form any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives, and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries.

EXECUTED as of the date(s) below by ASSIGNOR:

Mitsuya UTSUNO

宇津野 充弥

Signature

2020.9.24

Date

Yan ZHANG

Yan Zhang

Signature

2020.9.24

Date

Yoshio SUSA

須佐 至雄

Signature

2020.9.28

Date

Atsuki FUKAZAWA

Signature

Date

Application Serial No.: _____

Docket No.: PAT-JPN-0490-US-NP

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Title: SUBSTRATE PROCESSING DEVICE HAVING CONNECTION PLATES,
SUBSTRATE PROCESSING METHOD

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EXECUTED as of the date(s) below by ASSIGNOR:

Mitsuya UTSUNO

Signature

Date

Yan ZHANG

Signature

Date

Yoshio SUSA

Signature

Date

Atsuki FUKAZAWA



October 1st 2020

Signature

Date